

WST2066

Dual N-Ch MOSFET

General Description

The WST2066 is the highest performance trench N-ch MOSFETs with extreme high cell density, which provide excellent RDSON and gate charge for most of the small power switching and load switch applications.

The WST2066 meet the RoHS and Green Product requirement with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

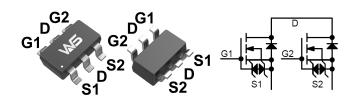
Product Summery

BVDSS	RDSON	ID
20V	16mΩ	7.2A

Applications

- Power management in portable and battery operated products
- One cell battery pack protection
- ESD:2KV

SOT-23-6L Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units	
V _{DS}	Drain-Source Voltage	20	V	
V _{GS}	Gate-Source Voltage	±12	V	
I₀@T₀=25℃	Continuous Drain Current, V _{GS} @ 4.5V ¹	7.2	A	
I _D @T _C =70℃	Continuous Drain Current, V _{GS} @ 4.5V ¹	5.8	A	
I _{DM}	Pulsed Drain Current ²	20	A	
P _D @T _A =25℃	Total Power Dissipation ³	1.4	W	
T _{STG}	Storage Temperature Range -55 to 18		°C	
TJ	Operating Junction Temperature Range	-55 to 150	°C	

Thermal Data

Symbol	Parameter	Тур.	Typ. Max.	
R _{θJA}	Thermal Resistance Junction-ambient ¹		150	°C/W
R _{eJC}	Thermal Resistance Junction-Case ¹		70	°C/W



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Electrical Characteristics (T_J=25 \odot , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	20			V
$\triangle BV_{DSS} / \triangle T_J$	BVDSS Temperature Coefficient	Reference to 25 $^\circ\!\mathrm{C}$, I_D=1mA		0.028		V/℃
		V _{GS} =4.5V , I _D =6.7A		16	18	
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =2.5V , I _D =5.2A		20	25	mΩ
		V _{GS} =1.8V , I _D =3A		30	40	
V _{GS(th)}	Gate Threshold Voltage		0.3	0.6	1.5	V
$ riangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	—V _{GS} =V _{DS} , I _D =250uA		-3.21		mV/°C
	Drain-Source Leakage Current	V _{DS} =16V , V _{GS} =0V , T _J =25℃			1	
I _{DSS}		V _{DS} =16V , V _{GS} =0V , T _J =55℃			5	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} = \pm 12V , V_{DS} =0V			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =5A		8		S
R _g	Gate Resistance	V_{DS} =0V , V_{GS} =0V , f=1MHz		4	6	Ω
Qg	Total Gate Charge (4.5V)	V _{DS} =10V , V _{GS} =4.5V , I _D =6.7A		13	17	
Q _{gs}	Gate-Source Charge			1.5	2.5	nC
Q _{gd}	Gate-Drain Charge			1.8	2.9	
T _{d(on)}	Turn-On Delay Time	V _{DD} =10V , V _{GEN} =4.5V , R _G =6Ω I _D =1.0A ,R∟=30Ω.		6.1		
Tr	Rise Time			9.7		
T _{d(off)}	Turn-Off Delay Time			26		ns
T _f	Fall Time			5.2		
C _{iss}	Input Capacitance	V _{DS} =10V , V _{GS} =0V , f=1MHz		610	725	
C _{oss}	Output Capacitance			140	175	pF
C _{rss}	Reverse Transfer Capacitance			130	150	1

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I _S	Continuous Source Current ^{1,4}				1.0	А
I _{SM}	Pulsed Source Current ^{2,4}	$V_G = V_D = 0V$, Force Current			20	А
V _{SD}	Diode Forward Voltage ²	$V_{GS}\text{=}0V$, $I_{SD}\text{=}1.3A$, $T_{J}\text{=}25^{\circ}\text{C}$			1.3	V
t _{rr}	Reverse Recovery Time			18		nS
Q _{rr}	Reverse Recovery Charge	lF=6.7A,dl/dt=100A/ μ s , T _J =25 $^{\circ}$ C		12		nC

Note :

1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%

3.The power dissipation is limited by 150 $^\circ\!\!\mathbb{C}$ junction temperature

4. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



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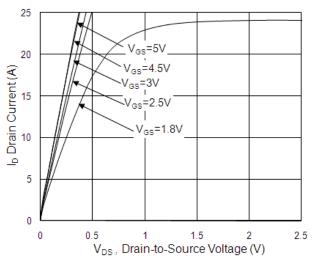


Fig.1 Typical Output Characteristics

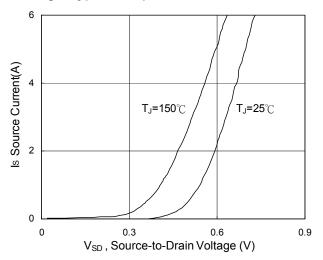


Fig.3 Forward Characteristics of reverse

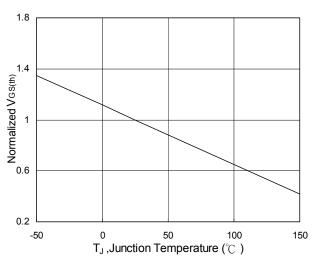


Fig.5 $V_{GS(th)}$ vs. T_J

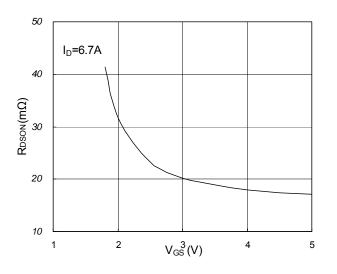


Fig.2 On-Resistance vs. Gate-Source

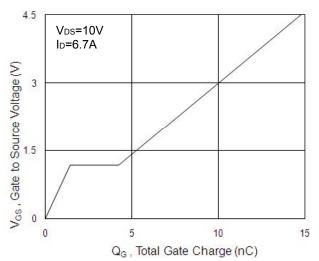


Fig.4 Gate-Charge Characteristics

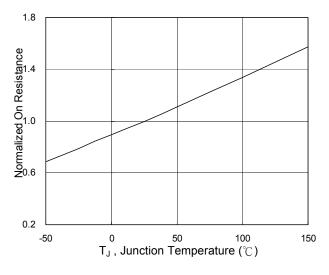


Fig.6 Normalized R_{DSON} vs. T_{J}



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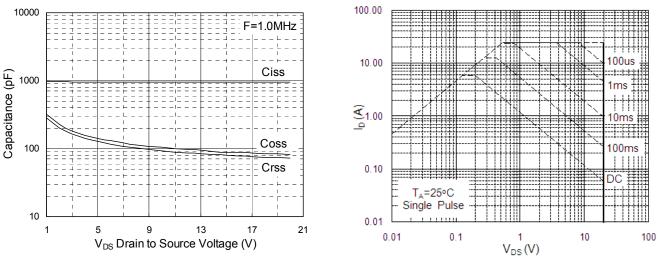
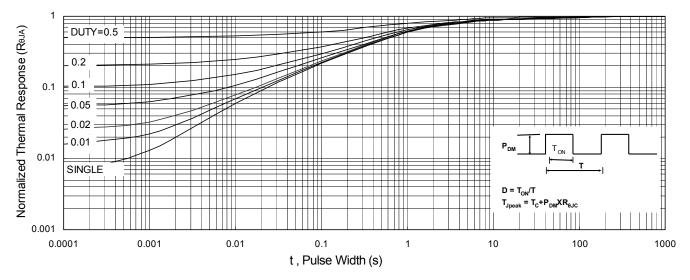
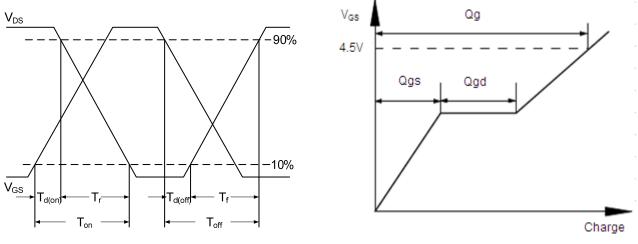


Fig.7 Capacitance

Fig.8 Safe Operating Area







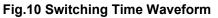


Fig.11 Gate Charge Waveform



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